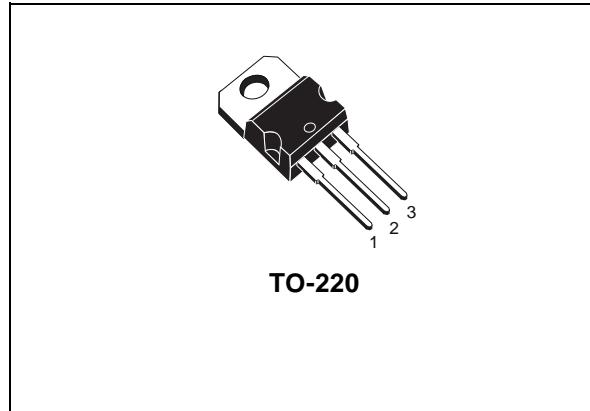
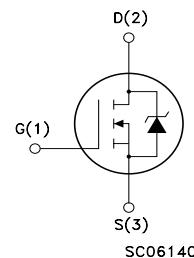


**MTP3055E****N-CHANNEL 60V - 0.1Ω - 12A TO-220****STripFET™ POWER MOSFET**

TYPE	V <sub>DSS</sub>	R <sub>D(on)</sub>	I <sub>D</sub>
MTP3055E	60 V	< 0.15 Ω	12 A

- TYPICAL R<sub>D(on)</sub> = 0.1Ω
- AVALANCHE RUGGED TECHNOLOGY
- 100% AVALANCHE TESTED
- 175°C OPERATING TEMPERATURE
- APPLICATION ORIENTED CHARACTERIZATION

**TO-220****INTERNAL SCHEMATIC DIAGRAM**

SC06140

**APPLICATIONS**

- HIGH CURRENT, HIGH SPEED SWITCHING
- SOLENOID AND RELAY DRIVERS
- REGULATORS
- DC-DC & DC-AC CONVERTERS
- MOTOR CONTROL, AUDIO AMPLIFIERS
- AUTOMOTIVE ENVIRONMENT (INJECTION, ABS, AIR-BAG, LAMPDRIVERS, Etc.)

**ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	60	V
V <sub>DGR</sub>	Drain-gate Voltage (R <sub>GS</sub> = 20 kΩ)	60	V
V <sub>GS</sub>	Gate- source Voltage	±20	V
I <sub>D</sub>	Drain Current (continuous) at T <sub>C</sub> = 25°C	12	A
I <sub>Dm</sub>	Drain Current (pulsed) at T <sub>C</sub> = 100°C	9	A
I <sub>DM</sub> (●)	Drain Current (pulsed)	48	A
P <sub>TOT</sub>	Total Dissipation at T <sub>C</sub> = 25°C	40	W
T <sub>stg</sub>	Storage Temperature	-65 to 175	°C
T <sub>j</sub>	Max. Operating Junction Temperature	175	°C

(●) Pulse width limited by safe operating area

First digit of the datecode being Z or K identifies silicon characterized in this datasheet

## MTP3055E

### THERMAL DATA

Rthj-case	Thermal Resistance Junction-case Max	3.75	°C/W
Rthj-amb	Thermal Resistance Junction-ambient Max	62.5	°C/W
Rthc-s	Thermal Resistance Case-sink Typ	0.5	°C/W
T <sub>I</sub>	Maximum Lead Temperature For Soldering Purpose	300	°C

### AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I <sub>AR</sub>	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T <sub>jmax</sub> )	12	A
E <sub>AS</sub>	Single pulse Avalanche Energy (starting T <sub>j</sub> = 25°C, I <sub>D</sub> = I <sub>AR</sub> , V <sub>DD</sub> = 25 V)	50	mJ

### ELECTRICAL CHARACTERISTICS (T<sub>CASE</sub> = 25 °C UNLESS OTHERWISE SPECIFIED) OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V(BR)DSS	Drain-source Breakdown Voltage	I <sub>D</sub> = 250 μA, V <sub>GS</sub> = 0	60			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = Max Rating V <sub>DS</sub> = Max Rating x 0.8, T <sub>C</sub> = 125 °C			1 10	μA μA
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ±20V			±100	nA

### ON (1)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	2.9	4	V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 7 A		0.1	0.15	Ω
I <sub>D(on)</sub>	On State Drain Current	V <sub>DS</sub> > I <sub>D(on)</sub> x R <sub>DS(on)max</sub> V <sub>GS</sub> = 10V	12			A

### DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g <sub>fs</sub> (1)	Forward Transconductance	V <sub>DS</sub> = I <sub>D(on)</sub> x R <sub>DS(on)max</sub> , I <sub>D</sub> = 6 A	4	6		S
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, f = 1 MHz, V <sub>GS</sub> = 0		760		pF
C <sub>oss</sub>	Output Capacitance			100		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			30		pF

## ELECTRICAL CHARACTERISTICS (CONTINUED)

## SWITCHING RESISTIVE LOAD

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Time	$V_{DD} = 30 \text{ V}$ , $I_D = 7 \text{ A}$		20		ns
$t_r$	Rise Time	$R_G = 50\Omega$ $V_{GS} = 10\text{V}$		65		ns
$t_{d(off)}$	Turn-off-Delay Time	(see test circuit)		70		ns
$t_f$	Fall Time			35		ns
$Q_g$	Total Gate Charge	$I_D = 12 \text{ A}$ , $V_{GS} = 10 \text{ V}$ ,		15		nC
$Q_{gs}$	Gate-Source Charge	$V_{DD} = 40\text{V}$		7		nC
$Q_{gd}$	Gate-Drain Charge	(see test circuit)		5		nC

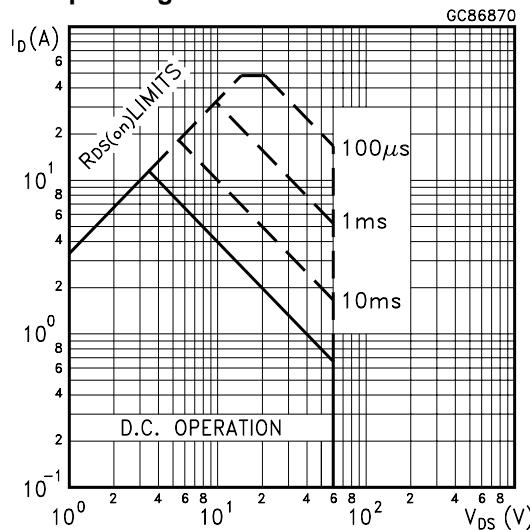
## SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain Current				12	A
$I_{SDM}$ (2)	Source-drain Current (pulsed)				48	A
$V_{SD}$ (1)	Forward On Voltage	$I_{SD} = 12 \text{ A}$ , $V_{GS} = 0$			2	V
$t_{rr}$	Reverse Recovery Time	$I_{SD} = 12 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ ,		65		ns
$Q_{rr}$	Reverse Recovery Charge	$V_{DD} = 30 \text{ V}$ , $T_j = 150^\circ\text{C}$		0.17		$\mu\text{C}$

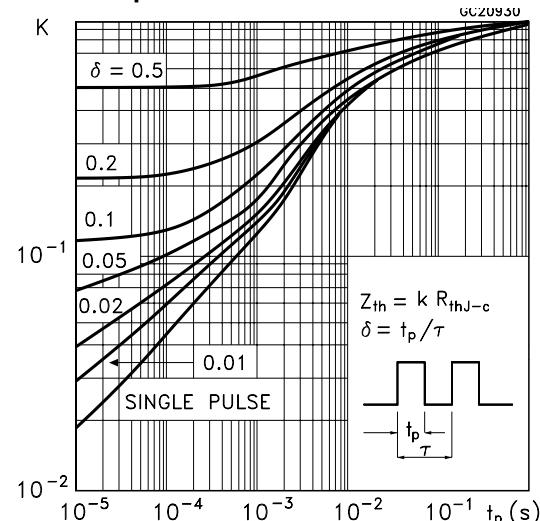
Note: 1. Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %.

2. Pulse width limited by safe operating area.

## Safe Operating Area

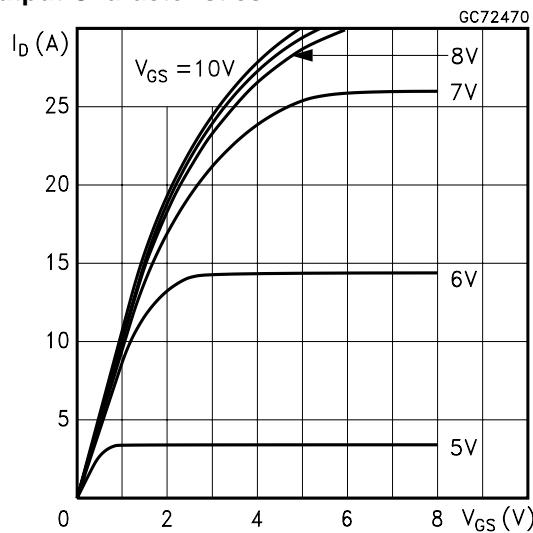


## Thermal Impedance

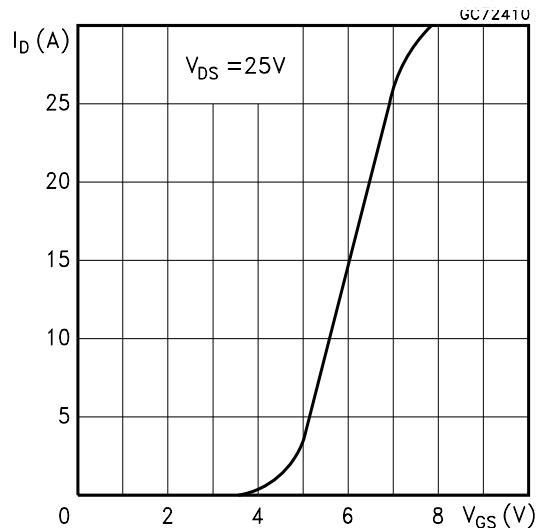


## MTP3055E

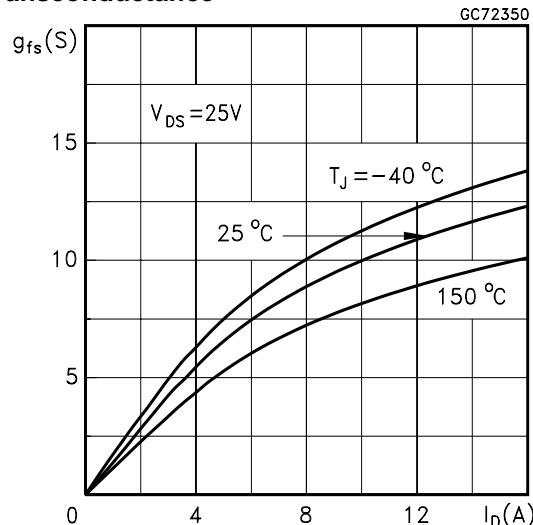
### Output Characteristics



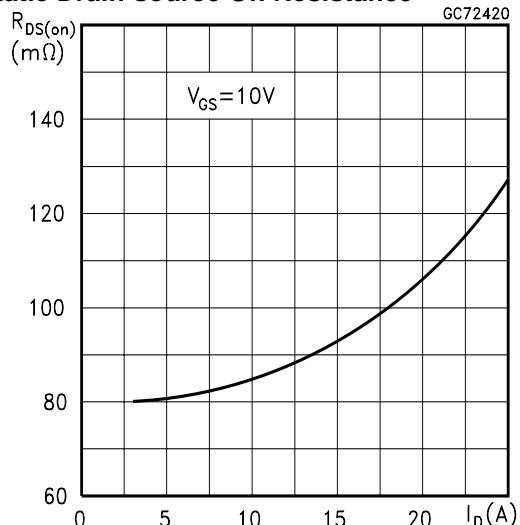
### Transfer Characteristics



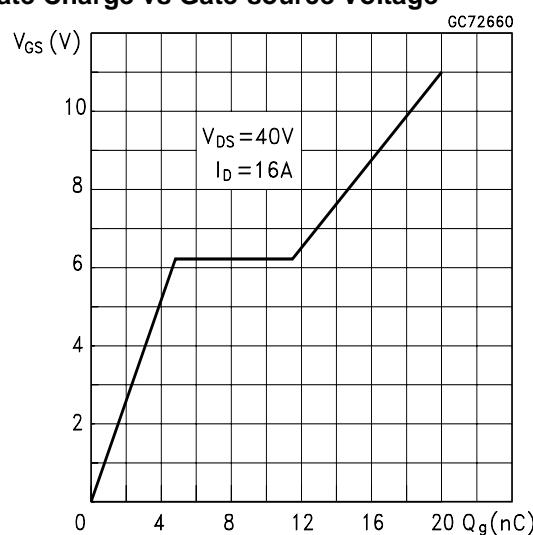
### Transconductance



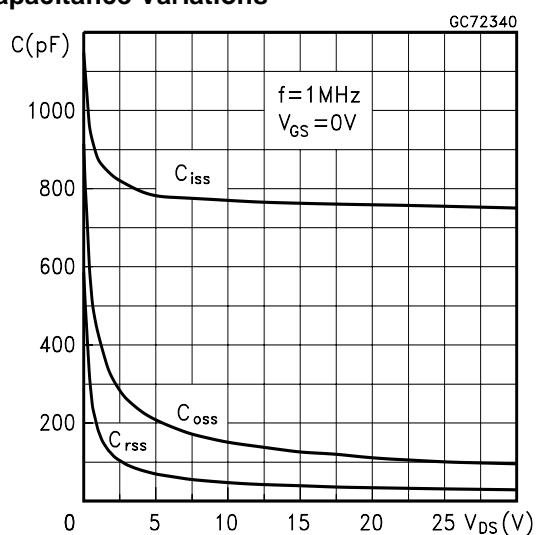
### Static Drain-source On Resistance



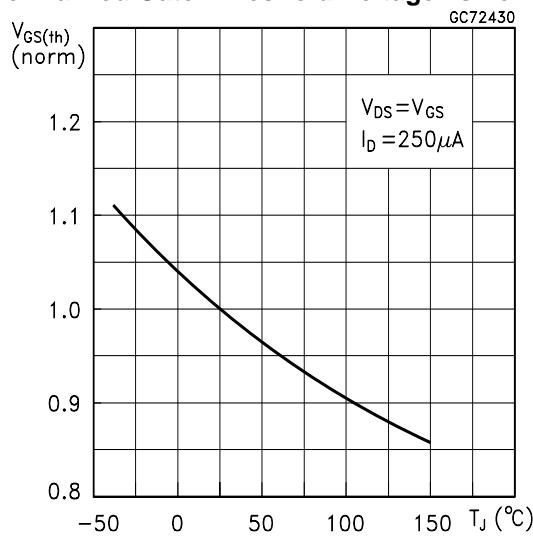
### Gate Charge vs Gate-source Voltage



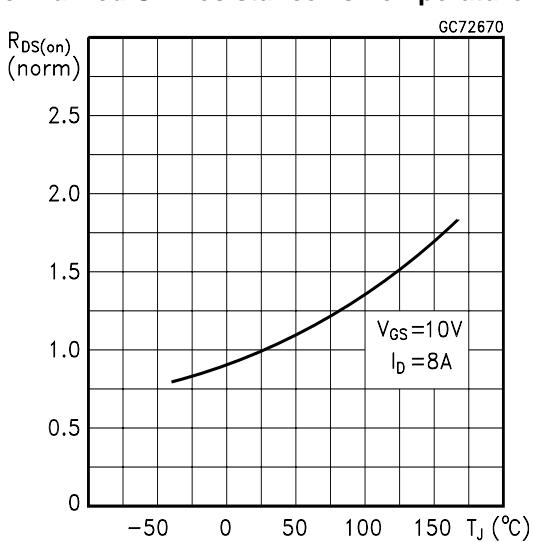
### Capacitance Variations



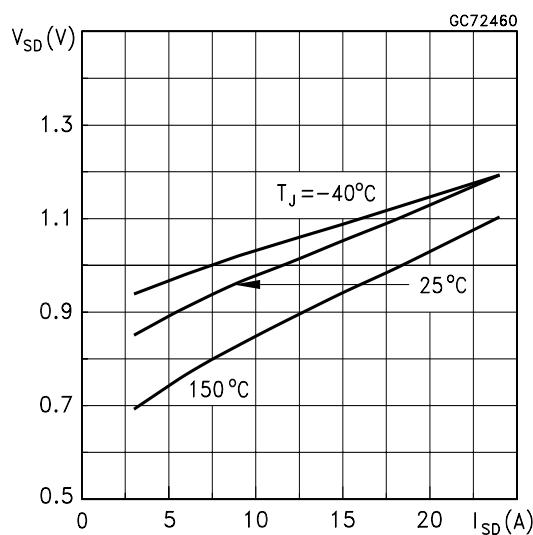
**Normalized Gate Threshold Voltage vs Temp.**



**Normalized On Resistance vs Temperature**

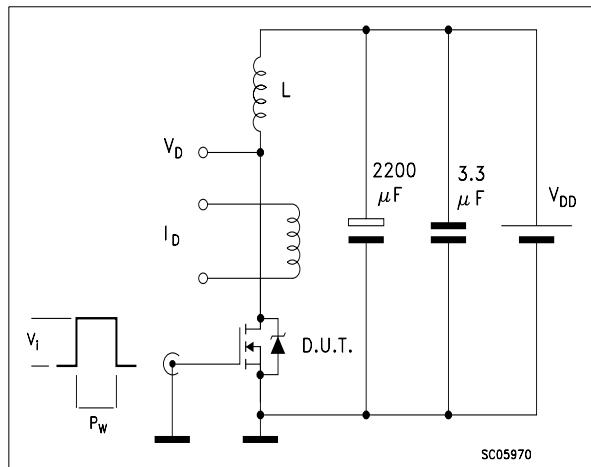


**Source-drain Diode Forward Characteristics**

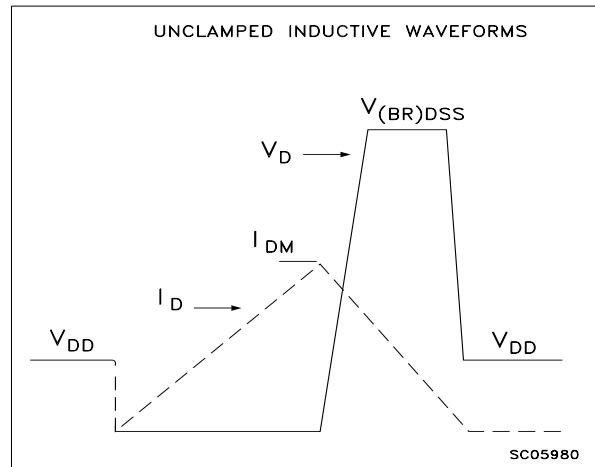


## MTP3055E

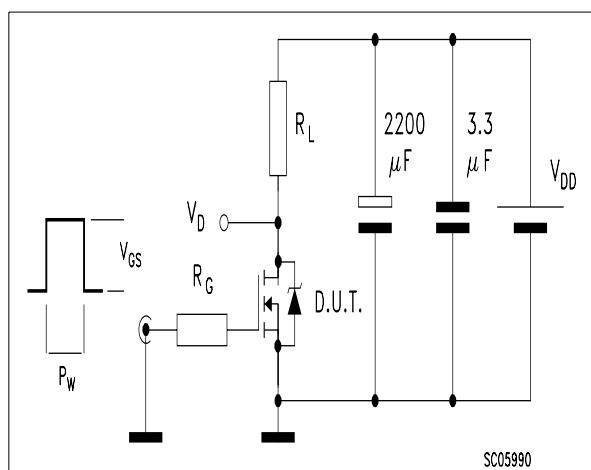
**Fig. 1:** Unclamped Inductive Load Test Circuit



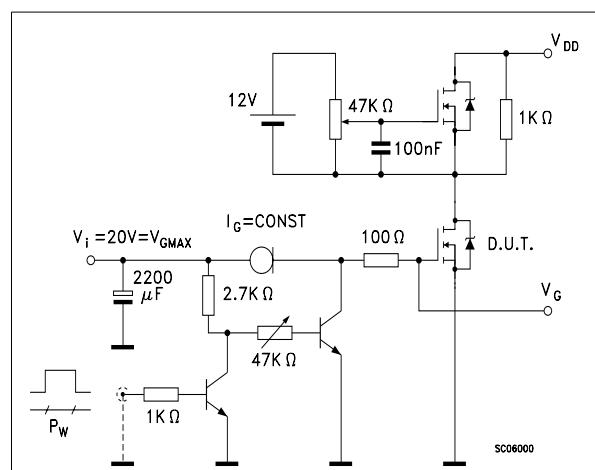
**Fig. 2:** Unclamped Inductive Waveform



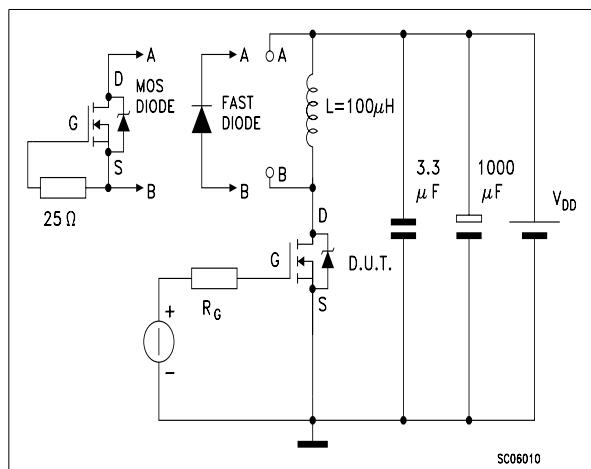
**Fig. 3:** Switching Times Test Circuit For Resistive Load



**Fig. 4:** Gate Charge test Circuit

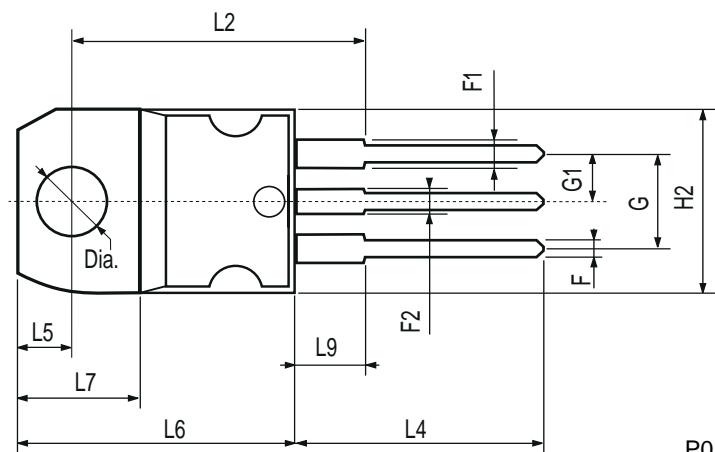
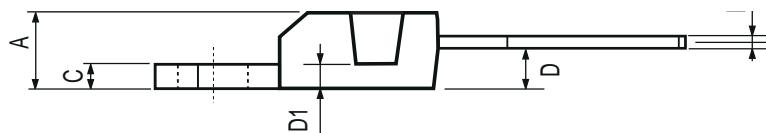


**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Recovery Times



## TO-220 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
C	1.23		1.32	0.048		0.051
D	2.40		2.72	0.094		0.107
D1		1.27			0.050	
E	0.49		0.70	0.019		0.027
F	0.61		0.88	0.024		0.034
F1	1.14		1.70	0.044		0.067
F2	1.14		1.70	0.044		0.067
G	4.95		5.15	0.194		0.203
G1	2.4		2.7	0.094		0.106
H2	10.0		10.40	0.393		0.409
L2		16.4			0.645	
L4	13.0		14.0	0.511		0.551
L5	2.65		2.95	0.104		0.116
L6	15.25		15.75	0.600		0.620
L7	6.2		6.6	0.244		0.260
L9	3.5		3.93	0.137		0.154
DIA.	3.75		3.85	0.147		0.151



Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

© The ST logo is a registered trademark of STMicroelectronics

© 2002 STMicroelectronics - Printed in Italy - All Rights Reserved  
STMicroelectronics GROUP OF COMPANIES

Australia - Brazil - Canada - China - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco  
Singapore - Spain - Sweden - Switzerland - United Kingdom - United States.

© <http://www.st.com>